

Amendments to the Specification:

On page 1, the title should be amended as follows:

ULTRA-LOW DIELECTRICS FILM FOR COPPER INTERCONNECT

On page 1, after the title and before the line beginning “BACKGROUND OF THE INVENTION” please insert the following paragraph:

This is a 371 filing of International Patent Application No. PCT/KR2004/001092 filed May 12, 2004 and published on June 16, 2005 under publication number WO 2005/055306 A and claims priority benefits from South Korean Patent Application No. KR 10-2003-0086244 filed December 1, 2003.